

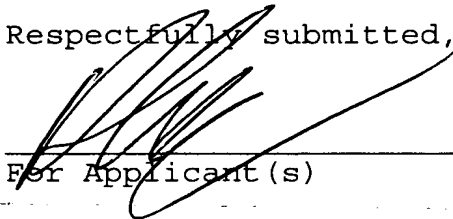
Remarks:

The preliminary amendment is being presented to make certain stylistic/typographical changes.

Claims 1 and 4 have been amended. A marked-up version of the claims is attached hereto on a separate page. Support for the change to claim 1 can be found in Fig. 1 and on page 10, lines 2-5 of the specification. The change to claim 4, is defining the acronym "AMB" as active metallic brazed.

Please charge any other fees which might be due with respect to Sections 1.16 and 1.17 to the Deposit Account of Lerner & Greenberg P.A., No. 12-1099.

Respectfully submitted,



For Applicant(s)

AKD:cgm

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Marked-up version of the claims:

Claim 1 (amended). A semiconductor module, comprising:

a substrate body having an insulating ceramic layer with a top side, and a metal layer fixedly joined to said top side of said insulating ceramic layer; [and]

at least one connection conductor joined to said metal layer by welding; and

at least one semiconductor component disposed directly on said substrate body facing said metal layer[, said semiconductor component having at least one connection conductor joined to said metal layer by welding].

Claim 4 (amended). The semiconductor module according to claim 3, wherein said substrate body is at least one of a direct copper bonded substrate and an [AMB] active metallic brazed substrate.

Marked-up version of the specification:

Replace the paragraph between page ⁵~~4~~, line 19 and page ⁵~~4~~, line 21 with the following: -- It is particularly advantageous in this context for the substrate body to be configured as a DCB substrate or an [AMB] active metallic brazed (AMB) substrate.-